

NGP200 Non-Silicone Gap Pad

NGP200 is a non-silicone, thermally conductive material for use at a thermal interface. Excellent properties are obtained from NGP200 due to the use of metal oxide powders. NGP200 is electrically insulative.

- Silicone free with two natural tack sides for easy handling
- Good thermal conductivity; 2.0 W/m.K
- Good flexibility, strength and high elastic resilience
- Flame retardant; meets UL94 V-0

Approvals	RoHS Compliant (2015/863/EU): UL Approval:	Yes Meets UL94 V-0
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Typical Properties	Colour: Density @ 20°C (g/ml): Thickness (mm) Hardness (Shore C) Tensile Strength (MPa): Thermal Conductivity: Temperature Range: Thermal Resistance (°C.in ² /W): Elongation (%): Volume Resistivity (Ω·cm): Dielectric Strength (kV/mm): Dielectric Constant @1MHz: Dielectric Loss: Compression Ratio (% @ 50psi): Flame Retardancy	Grey 2.7 0.5 – 1.0 35 0.19 2.0 W/m.K -40°C to +150°C 0.70 167 1.0 x 10 ⁸ 8 5 0.1 25 Meets UL94 V-0
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<u>Description</u>	<u>Order Code</u>	<u>Dimension of Gap Pad</u>
<u>Gap Pad</u>	NGP200S	200 x 200 x 0.5 mm
<u>Gap Pad</u>	NGP200SL	200 x 200 x 1.0 mm

Revision 3: Jan 2019